

Title (en)

Method for the fabrication of a multi-layered patina and said multi-layered patina

Title (de)

Multischicht-Patina und Verfahren zum Herstellen einer multischicht-Patina

Title (fr)

Procédé de fabrication d'une patine ayant une structure multicouchee et patine avec cette structure multicouchee

Publication

EP 1643006 A3 20060906 (EN)

Application

EP 05020621 A 20050921

Priority

FI 20041256 A 20040929

Abstract (en)

[origin: EP1643006A2] The invention relates to a method for forming a patina surface on a substrate, which is preferably made of copper or copper alloy. According to the method, the patina surface is formed on top of the surface of the substrate material in at least two different layers of corrosive patination material, of which the colour and/or composition differ from each other. The invention also relates to the patina, which is formed as at least two layers.

IPC 8 full level

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IPC 8 main group level

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CPC (source: EP)

C23C 8/02 (2013.01); **C23C 8/10** (2013.01); **C23C 22/63** (2013.01); **C23C 22/76** (2013.01); **C23C 28/04** (2013.01)

Citation (search report)

- [X] US 6063480 A 20000516 - HOKAZONO TAKASHI [JP], et al
- [X] DE 19542410 A1 19960515 - FURUKAWA ELECTRIC CO LTD [JP]
- [A] US 6176905 B1 20010123 - PRIGGEMEYER SONJA [DE], et al & PROC ELECTROCHEM SOC 1986 ELECTROCHEMICAL SOC, PENNINGTON, NJ, USA, vol. 86-6, 1986, pages 206 - 215
- [X] DATABASE COMPENDEX [online] ENGINEERING INFORMATION, INC., NEW YORK, NY, US; FRANEY J P ET AL: "STRUCTURE OF COPPER PATINA PRODUCED BY EXTENDED ATMOSPHERIC EXPOSURE", XP002389243, Database accession no. EIX87030047774
- [A] F. NOLI, P. MISAEILIDES ET AL.: "investigation of artificially produced and natural copper patina layers", JOURNAL OF MATERIALS CHEMISTRY, vol. 13, 21 November 2003 (2003-11-21), pages 114 - 120, XP002389240

Cited by

JP2011021227A; CN104233276A; CN114323842A; CN112326955A

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